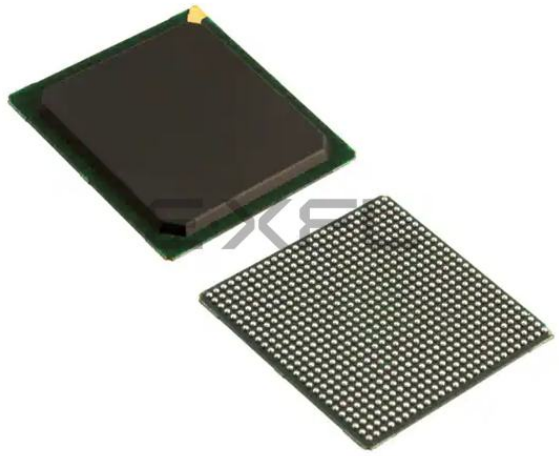

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	8064
Number of Logic Elements/Cells	-
Total RAM Bits	73728
Number of I/O	336
Number of Gates	500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax500-1fg676i

Calculating Power Dissipation

Table 2-3 • **Standby Current**

Device	Temperature	ICCA	ICCDA	ICCBANK		ICCPLL	ICCCP[1]		IIH, IIL, IOZ[2]	Units
		Standby Current (Core)	Standby Current, Differential I/O	Standby Current per I/O Bank		Standby Current per PLL	Standby Current, Charge Pump			
				2.5 V VCCI	3.3 V VCCI		Active	Bypassed Mode		
AX125	Typical at 25°C	1.5	1.5	0.2	0.3	0.2	0.3	0.01	±0.01	mA
	70°C	15	6	0.5	0.75	1	0.4	0.01	±0.01	mA
	85°C	25	6	0.6	0.8	1	0.4	0.2	±0.01	mA
	125°C	50	8	1	1.5	2	0.4	0.5	±0.01	mA
AX250	Typical at 25°C	1.5	1.4	0.25	0.4	0.2	0.3	0.01	±0.01	mA
	70°C	30	7	0.8	0.9	1	0.4	0.01	±0.01	mA
	85°C	40	7	0.8	1	1	0.4	0.2	±0.01	mA
	125°C	70	9	1.3	1.8	2	0.4	0.5	±0.01	mA
AX500	Typical at 25°C	5	1.4	0.4	0.75	0.2	0.3	0.01	±0.01	mA
	70°C	60	7	1	1.5	1	0.4	0.01	±0.01	mA
	85°C	80	7	1	1.9	1	0.4	0.2	±0.01	mA
	125°C	180	9	1.75	2.5	1.5	0.4	0.5	±0.01	mA
AX1000	Typical at 25°C	7.5	1.5	0.5	1.25	0.2	0.3	0.01	±0.01	mA
	70°C	80	8	1.5	3	1	0.4	0.01	±0.01	mA
	85°C	120	8	1.5	3.4	1	0.4	0.2	±0.01	mA
	125°C	200	10	3	4	1.5	0.4	0.5	±0.01	mA
AX2000	Typical at 25°C	20	1.6	0.7	1.5	0.2	0.3	0.01	±0.01	mA
	70°C	160	10	2	7	1	0.4	0.01	±0.01	mA
	85°C	200	10	3	8	1	0.4	0.2	±0.01	mA
	125°C	500	15	4	10	1.5	0.4	0.5	±0.01	mA

Notes:

1. *ICCCP Active is the ICCDA or the Internal Charge Pump current. ICCCP Bypassed mode is the External Charge Pump current IIH (VPUMP pin).*
2. *IIH, IIL, or IOZ values are measured with inputs at the same level as VCCI for IIH and GND for IIL and IOZ.*

User-Defined Supply Pins

VREF **Supply Voltage**

Reference voltage for I/O banks. VREF pins are configured by the user from regular I/O pins; VREF pins are not in fixed locations. There can be one or more VREF pins in an I/O bank.

Global Pins

HCLKA/B/C/D **Dedicated (Hardwired) Clocks A, B, C and D**

These pins are the clock inputs for sequential modules or north PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. This input is directly wired to each R-cell and offers clock speeds independent of the number of R-cells being driven. When the HCLK pins are unused, it is recommended that they are tied to ground.

CLKE/F/G/H **Routed Clocks E, F, G, and H**

These pins are clock inputs for clock distribution networks or south PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. The clock input is buffered prior to clocking the R-cells. When the CLK pins are unused, Microsemi recommends that they are tied to ground.

JTAG/Probe Pins

PRA/B/C/D **Probe A, B, C and D**

The Probe pins are used to output data from any user-defined design node within the device (controlled with Silicon Explorer II). These independent diagnostic pins can be used to allow real-time diagnostic output of any signal path within the device. The pins' probe capabilities can be permanently disabled to protect programmed design confidentiality. The probe pins are of LVTTL output levels.

TCK **Test Clock**

Test clock input for JTAG boundary-scan testing and diagnostic probe (Silicon Explorer II).

TDI **Test Data Input**

Serial input for JTAG boundary-scan testing and diagnostic probe. TDI is equipped with an internal 10 kΩ pull-up resistor.

TDO **Test Data Output**

Serial output for JTAG boundary-scan testing.

TMS **Test Mode Select**

The TMS pin controls the use of the IEEE 1149.1 boundary-scan pins (TCK, TDI, TDO, TRST). TMS is equipped with an internal 10 kΩ pull-up resistor.

TRST **Boundary Scan Reset Pin**

The TRST pin functions as an active-low input to asynchronously initialize or reset the boundary scan circuit. The TRST pin is equipped with a 10 kΩ pull-up resistor.

Special Functions

LP **Low Power Pin**

The LP pin controls the low power mode of Axcelerator devices. The device is placed in the low power mode by connecting the LP pin to logic high. To exit the low power mode, the LP pin must be set Low. Additionally, the LP pin must be set Low during chip powering-up or chip powering-down operations. See "Low Power Mode" on page 2-106 for more details.

NC **No Connection**

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

Timing Characteristics

***Table 2-22* • 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 1 (8 mA) / Low Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		14.28		16.27		19.13	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		15.25		17.37		20.42	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		14.26		16.24		19.09	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.56		1.57		1.58	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		1.95		1.96		1.97	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		039		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

***Table 2-22* • 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 2 (12 mA) / Low Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		12.14		13.83		16.26	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		12.43		14.16		16.65	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		12.17		13.86		16.30	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.73		1.74		1.75	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.22		2.23		2.24	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.38		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

***Table 2-69* • AX2000 Predicted Routing Delays**
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		–2 Speed	–1 Speed	Std Speed	
Parameter	**Description**	**Typical**	**Typical**	**Typical**	**Units**
Predicted Routing Delays					
t_{DC}	DirectConnect Routing Delay, FO1	0.12	0.13	0.15	ns
t_{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t_{RD1}	Routing delay for FO1	0.50	0.56	0.66	ns
t_{RD2}	Routing delay for FO2	0.59	0.67	0.79	ns
t_{RD3}	Routing delay for FO3	0.70	0.80	0.94	ns
t_{RD4}	Routing delay for FO4	0.76	0.87	1.02	ns
t_{RD5}	Routing delay for FO5	0.98	1.11	1.31	ns
t_{RD6}	Routing delay for FO6	1.48	1.68	1.97	ns
t_{RD7}	Routing delay for FO7	1.65	1.87	2.20	ns
t_{RD8}	Routing delay for FO8	1.73	1.96	2.31	ns
t_{RD16}	Routing delay for FO16	2.58	2.92	3.44	ns
t_{RD32}	Routing delay for FO32	4.24	4.81	5.65	ns

***Table 2-80* • PLL Interface Signals**

Signal Name	Type	User Accessible	Allowable Values	Function
RefCLK	Input	Yes		Reference Clock for the PLL
FB	Input	Yes		Feedback port for the PLL
PowerDown	Input	Yes		PLL power down control
			0	PLL powered down
			1	PLL active
DIVI[5:0]	Input	Yes	1 to 64, in unsigned binary notation offset by -1	Sets value for feedback divider (multiplier)
DIVJ[5:0]	Input	Yes		Sets value for CLK1 divider
LowFreq	Input	Yes		Input frequency range selector
			0	50–200 MHz
			1	14–50 MHz
Osc[2:0]	Input	Yes		Output frequency range selector
			XX0	400–1000 MHZ
			001	200–400 MHZ
			011	100–200 MHZ
			101	50–100 MHZ
			111	20–50 MHZ
DelayLine[4:0]	Input	Yes	–15 to +15 (increments), in signed-and-magnitude binary representation	Clock Delay (positive/negative) in increments of 250 ps, with maximum value of ± 3.75 ns
FBMuxSel	Input	No		Selects the source for the feedback input
REFSEL	Input	No		Selects the source for the reference clock
OUTSEL	Input	No		Selects the source for the routed net output
PLLSEL	Input	No		ROOTSEL & PLLSEL are used to select the source of the global clock network
ROOTSEL	Input	No		
Lock	Output	Yes		High value indicates PLL has locked
CLK1	Output	Yes		PLL clock output
CLK2	Output	Yes		PLL clock output

Note: If the input RefClk is taken outside its operating range, the outputs Lock, CLK1 and CLK2 are indeterminate.

***Table 2-98* • One FIFO Block**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
FIFO Module Timing								
t_{WSU}	Write Setup		11.40		12.98		15.26	ns
t_{WHD}	Write Hold		0.22		0.25		0.30	ns
t_{WCKH}	WCLK High		0.75		0.75		0.75	ns
t_{WCKL}	WCLK Low		0.88		0.88		0.88	ns
t_{WCKP}	Minimum WCLK Period	1.63		1.63		1.63		ns
t_{RSU}	Read Setup		11.63		13.25		15.58	ns
t_{RHD}	Read Hold		0.00		0.00		0.00	ns
t_{RCKH}	RCLK High		0.77		0.77		0.77	ns
t_{RCKL}	RCLK Low		0.93		0.93		0.93	ns
t_{RCKP}	Minimum RCLK period	1.70		1.70		1.70		ns
t_{CLRHF}	Clear High		0.00		0.00		0.00	ns
t_{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t_{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t_{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t_{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.32		1.51		1.77	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		2.16		2.46		2.90	ns

Note: Timing data for this single block FIFO has a depth of 4,096. For all other combinations, use Microsemi's timing software.

throughout the fabric of the device and may be programmed by the user to thwart attempts to reverse engineer the device by attempting to exploit either the programming or probing interfaces. Both invasive and noninvasive attacks against an Axcelerator device that access or bypass these security fuses will destroy access to the rest of the device. (refer to the *Design Security in Nonvolatile Flash and Antifuse FPGAs* white paper).

Look for this symbol to ensure your valuable IP is protected with highest level of security in the industry.

Figure 2-69 • **FuseLock Logo**

To ensure maximum security in Axcelerator devices, it is recommended that the user program the device security fuse (SFUS). When programmed, the Silicon Explorer II testing probes are disabled to prevent internal probing, and the programming interface is also disabled. All JTAG public instructions are still accessible by the user.

For more information, refer to the *Implementation of Security in Actel Antifuse FPGAs* application note.

Global Set Fuse

The Global Set Fuse determines if all R-cells and I/O registers (InReg, OutReg, and EnReg) are either cleared or preset by driving the GCLR and GPSET inputs of all R-cells and I/O Registers (Figure 2-31 on page 2-58). Default setting is to clear all registers (GCLR = 0 and GPSET =1) at device power-up. When the GBSETFUS option is checked during FUSE file generation, all registers are preset (GCLR = 1 and GPSET= 0). A local CLR or PRESET will take precedence over this setting. Both pins are pulled High during normal device operation. For use details, see the Libero IDE online help.

Silicon Explorer II Probe Interface

Silicon Explorer II is an integrated hardware and software solution that, in conjunction with the Designer tools, allows users to examine any of the internal nets (except I/O registers) of the device while it is operating in a prototype or a production system. The user can probe up to four nodes at a time without changing the placement and routing of the design and without using any additional device resources. Highlighted nets in Designer's ChipPlanner can be accessed using Silicon Explorer II in order to observe their real time values.

Silicon Explorer II's noninvasive method does not alter timing or loading effects, thus shortening the debug cycle. In addition, Silicon Explorer II does not require relayout or additional MUXes to bring signals out to external pins, which is necessary when using programmable logic devices from other suppliers. By eliminating multiple place-and-route program cycles, the integrity of the design is maintained throughout the debug process.

Each member of the Axcelerator family has four external pads: PRA, PRB, PRC, and PRD. These can be used to bring out four probe signals from the Axcelerator device (note that the AX125 only has two probe signals that can be observed: PRA and PRB). Each core tile has up to two probe signals. To disallow probing, the SFUS security fuse in the silicon signature has to be programmed (see "Special Fuses" on page 2-108).

Silicon Explorer II connects to the host PC using a standard serial port connector. Connections to the circuit board are achieved using a nine-pin D-Sub connector (Figure 1-9 on page 1-7). Once the design has been placed-and-routed, and the Axcelerator device has been programmed, Silicon Explorer II can be connected and the Explorer software can be launched.

Silicon Explorer II comes with an additional optional PC hosted tool that emulates an 18-channel logic analyzer. Four channels are used to monitor four internal nodes, and 14 channels are available to probe external signals. The software included with the tool provides the user with an intuitive interface that allows for easy viewing and editing of signal waveforms.

Programming

Device programming is supported through the Silicon Sculptor II, a single-site, robust and compact device programmer for the PC. Up to four Silicon Sculptor IIs can be daisy-chained and controlled from a single PC host. With standalone software for the PC, Silicon Sculptor II is designed to allow concurrent programming of multiple units from the same PC when daisy-chained.

Silicon Sculptor II programs devices independently to achieve the fastest programming times possible. Each fuse is verified by Silicon Sculptor II to ensure correct programming. Furthermore, at the end of programming, there are integrity tests that are run to ensure that programming was completed properly. Not only does it test programmed and nonprogrammed fuses, Silicon Sculptor II also provides a self-test to test its own hardware extensively.

Programming an Axcelerator device using Silicon Sculptor II is similar to programming any other antifuse device. The procedure is as follows:

1. Load the *.AFM file.
2. Select the device to be programmed.
3. Begin programming.

When the design is ready to go to production, Microsemi offers device volume-programming services either through distribution partners or via our In-House Programming Center.

In addition, BP Microsystems offers multi-site programmers that provide qualified support for Axcelerator devices.

For more details on programming the Axcelerator devices, please refer to the *Silicon Sculptor II User's Guide*.

FG256	
AX250 Function	**Pin Number**
Bank 6	
IO91NB6F6	L4
IO91PB6F6	M4
IO92NB6F6	L3
IO92PB6F6	M3
IO94NB6F6	P2
IO94PB6F6	N2
IO97NB6F6	J4
IO97PB6F6	K4
IO98NB6F6	N1
IO98PB6F6	P1
IO100NB6F6	L2
IO100PB6F6	M2
IO102NB6F6	L1
IO102PB6F6	M1
IO103NB6F6	J3
IO103PB6F6	K3
IO104NB6F6	J2
IO104PB6F6	K2
Bank 7	
IO107NB7F7	J1
IO107PB7F7	K1
IO108NB7F7	G2
IO108PB7F7	H2
IO111NB7F7	G3
IO111PB7F7	H3
IO112NB7F7	E1
IO112PB7F7	F1
IO113NB7F7	G1
IO114NB7F7	E2
IO114PB7F7	F2
IO115NB7F7	G4
IO115PB7F7	H4
IO116NB7F7	C1
IO116PB7F7	D1

FG256	
AX250 Function	**Pin Number**
IO117NB7F7	C2
IO117PB7F7	B1
IO118NB7F7	D2
IO118PB7F7	D3
IO119NB7F7	E3
IO119PB7F7	F3
Dedicated I/O	
VCCDA	E4
GND	A1
GND	A16
GND	B15
GND	B2
GND	D15
GND	E12
GND	E5
GND	F11
GND	F6
GND	G10
GND	G7
GND	G8
GND	G9
GND	H10
GND	H7
GND	H8
GND	H9
GND	J10
GND	J7
GND	J8
GND	J9
GND	K10
GND	K7
GND	K8
GND	K9
GND	L11
GND	L6

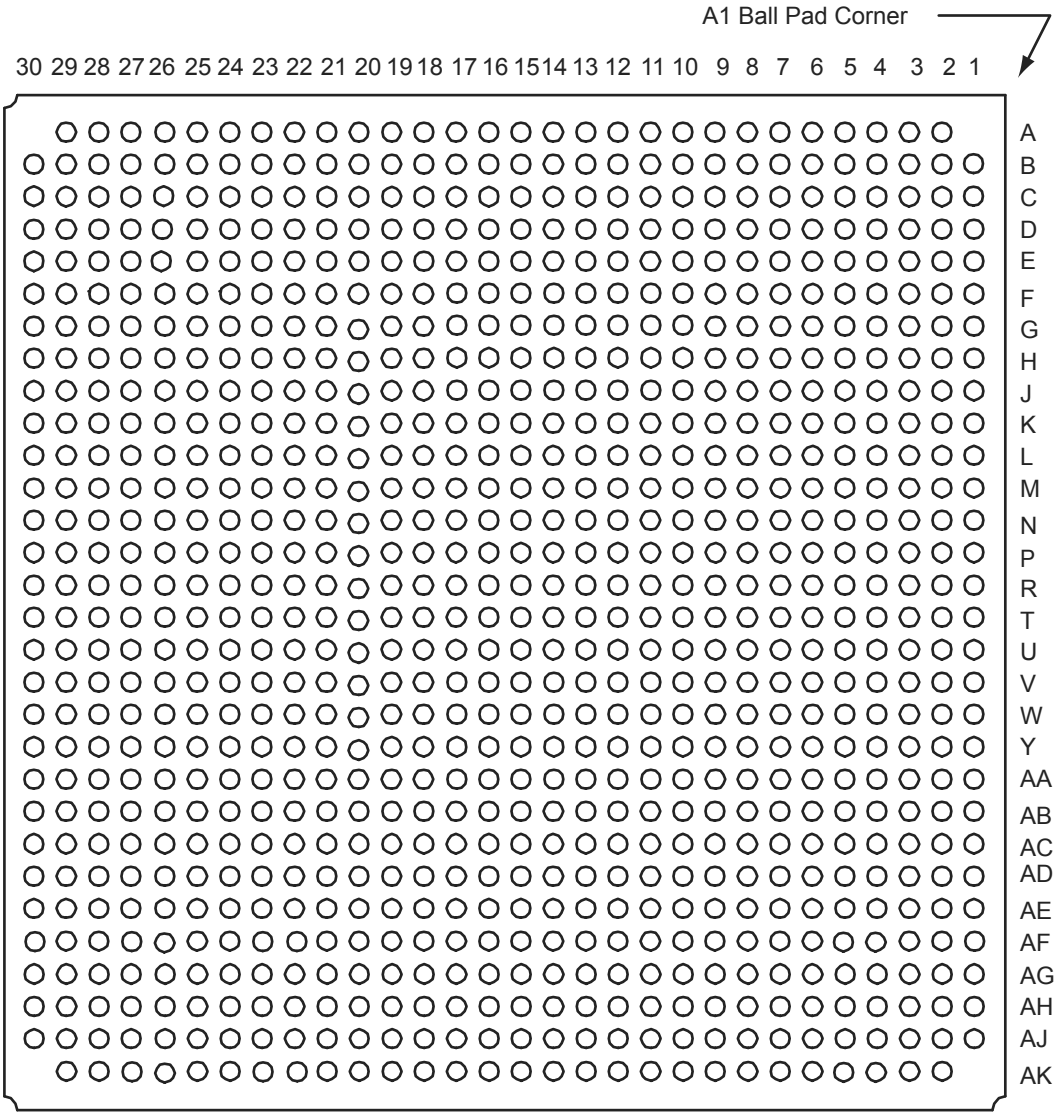
FG256	
AX250 Function	**Pin Number**
GND	M12
GND	M5
GND	P13
GND	P3
GND	R15
GND	R2
GND	T1
GND	T16
GND/LP	D4
PRA	D8
PRB	C8
PRC	N9
PRD	P9
TCK	D5
TDI	C6
TDO	C4
TMS	C3
TRST	C5
VCCA	D14
VCCA	F10
VCCA	F4
VCCA	F7
VCCA	F8
VCCA	F9
VCCA	G11
VCCA	G6
VCCA	H11
VCCA	H6
VCCA	J11
VCCA	J6
VCCA	K11
VCCA	K6
VCCA	L10
VCCA	L7
VCCA	L8

FG676	
AX1000 Function	**Pin Number**
GND	A8
GND	AC23
GND	AC4
GND	AD24
GND	AD3
GND	AE2
GND	AE25
GND	AF1
GND	AF13
GND	AF14
GND	AF19
GND	AF26
GND	AF8
GND	B2
GND	B25
GND	B26
GND	C24
GND	C3
GND	G20
GND	G7
GND	H1
GND	H19
GND	H26
GND	H8
GND	J18
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	K14
GND	K15
GND	K16
GND	K17
GND	L10
GND	L11

FG676	
AX1000 Function	**Pin Number**
GND	L12
GND	L13
GND	L14
GND	L15
GND	L16
GND	L17
GND	M10
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	N1
GND	N10
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N26
GND	P1
GND	P10
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P26
GND	R10
GND	R11

FG676	
AX1000 Function	**Pin Number**
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A25
NC	AC13
NC	AC14
NC	AF2
NC	AF25

FG896



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

CQ208	
AX500 Function	Pin Number
Bank 0	
IO03NB0F0	198
IO03PB0F0	199
IO04NB0F0	197
IO19NB0F1/HCLKAN	191
IO19PB0F1/HCLKAP	192
IO20NB0F1/HCLKBN	185
IO20PB0F1/HCLKBP	186
Bank 1	
IO21NB1F2/HCLKCN	180
IO21PB1F2/HCLKCP	181
IO22NB1F2/HCLKDN	174
IO22PB1F2/HCLKDP	175
IO23NB1F2	170
IO23PB1F2	171
IO37NB1F3	165
IO37PB1F3	166
IO39NB1F3	161
IO39PB1F3	162
IO41NB1F3	159
IO41PB1F3	160
Bank 2	
IO43NB2F4	151
IO43PB2F4	153
IO44NB2F4	152
IO44PB2F4	154
IO45PB2F4	148
IO46NB2F4	146
IO46PB2F4	147
IO48NB2F4	144
IO48PB2F4	145
IO57NB2F5	139
IO57PB2F5	140
IO58PB2F5	141
IO59NB2F5	137
IO59PB2F5	138
IO61NB2F5	132

CQ208	
AX500 Function	Pin Number
IO61PB2F5	134
IO62NB2F5	131
IO62PB2F5	133
Bank 3	
IO63NB3F6	127
IO63PB3F6	129
IO64NB3F6	126
IO64PB3F6	128
IO66NB3F6	122
IO66PB3F6	123
IO68NB3F6	120
IO68PB3F6	121
IO77NB3F7	116
IO77PB3F7	117
IO79NB3F7	114
IO79PB3F7	115
IO81NB3F7	110
IO81PB3F7	111
IO82NB3F7	108
IO82PB3F7	109
IO83NB3F7	106
IO83PB3F7	107
Bank 4	
IO84PB4F8	103
IO85NB4F8	100
IO86NB4F8	101
IO86PB4F8	102
IO87NB4F8	96
IO87PB4F8	97
IO101NB4F9	91
IO101PB4F9	92
IO103NB4F9/CLKEN	87
IO103PB4F9/CLKEP	88
IO104NB4F9/CLKFN	81
IO104PB4F9/CLKFP	82
Bank 5	
IO105NB5F10/CLKGN	76

CQ208	
AX500 Function	Pin Number
IO105PB5F10/CLKGP	77
IO106NB5F10/CLKHN	70
IO106PB5F10/CLKHP	71
IO107NB5F10	66
IO107PB5F10	67
IO119NB5F11	62
IO121NB5F11	60
IO121PB5F11	61
IO123NB5F11	56
IO123PB5F11	57
IO125NB5F11	54
IO125PB5F11	55
Bank 6	
IO127NB6F12	47
IO127PB6F12	49
IO128NB6F12	48
IO128PB6F12	50
IO129NB6F12	42
IO129PB6F12	43
IO130PB6F12	44
IO132NB6F12	40
IO132PB6F12	41
IO141NB6F13	35
IO141PB6F13	36
IO142PB6F13	37
IO143NB6F13	33
IO143PB6F13	34
IO145NB6F13	28
IO145PB6F13	30
IO146NB6F13	27
IO146PB6F13	29
Bank 7	
IO147NB7F14	23
IO147PB7F14	25
IO148NB7F14	22
IO148PB7F14	24
IO150NB7F14	18

CQ352	
AX250 Function	Pin Number
GND	21
GND	27
GND	33
GND	39
GND	45
GND	51
GND	57
GND	63
GND	69
GND	75
GND	81
GND	88
GND	89
GND	97
GND	103
GND	109
GND	115
GND	121
GND	133
GND	145
GND	151
GND	157
GND	163
GND	169
GND	176
GND	177
GND	186
GND	192
GND	198
GND	204
GND	210
GND	216
GND	222
GND	228
GND	234

CQ352	
AX250 Function	Pin Number
GND	240
GND	246
GND	252
GND	258
GND	264
GND	265
GND	274
GND	280
GND	286
GND	292
GND	298
GND	310
GND	322
GND	330
GND	334
GND	340
GND	345
GND	352
NC	91
NC	117
NC	130
NC	131
NC	148
NC	174
NC	268
NC	294
NC	307
NC	308
NC	327
NC	328
PRA	312
PRB	311
PRC	135
PRD	134
TCK	349

CQ352	
AX250 Function	Pin Number
TDI	348
TDO	347
TMS	350
TRST	351
VCCA	3
VCCA	14
VCCA	32
VCCA	56
VCCA	74
VCCA	87
VCCA	102
VCCA	114
VCCA	150
VCCA	162
VCCA	175
VCCA	191
VCCA	209
VCCA	233
VCCA	251
VCCA	263
VCCA	279
VCCA	291
VCCA	329
VCCA	339
VCCDA	2
VCCDA	44
VCCDA	90
VCCDA	116
VCCDA	132
VCCDA	149
VCCDA	178
VCCDA	221
VCCDA	266
VCCDA	293
VCCDA	309

CQ352	
AX2000 Function	Pin Number
IO182PB4F17	171
IO183NB4F17	166
IO183PB4F17	167
IO184NB4F17	164
IO184PB4F17	165
IO185NB4F17	160
IO185PB4F17	161
IO190NB4F17	158
IO190PB4F17	159
IO191NB4F17	154
IO191PB4F17	155
IO192NB4F17	152
IO192PB4F17	153
IO207NB4F19	146
IO207PB4F19	147
IO212NB4F19/CLKEN	142
IO212PB4F19/CLKEP	143
IO213NB4F19/CLKFN	136
IO213PB4F19/CLKFP	137
Bank 5	
IO214NB5F20/CLKGN	128
IO214PB5F20/CLKGP	129
IO215NB5F20/CLKHN	122
IO215PB5F20/CLKHP	123
IO217NB5F20	118
IO217PB5F20	119
IO236NB5F22	110
IO236PB5F22	111
IO237NB5F22	112
IO237PB5F22	113
IO238NB5F22	104
IO238PB5F22	105
IO239NB5F22	106
IO239PB5F22	107
IO240NB5F22	100

CQ352	
AX2000 Function	Pin Number
IO240PB5F22	101
IO242NB5F22	94
IO242PB5F22	95
IO243NB5F22	98
IO243PB5F22	99
IO244NB5F22	92
IO244PB5F22	93
Bank 6	
IO257PB6F24	86
IO258NB6F24	84
IO258PB6F24	85
IO261NB6F24	82
IO261PB6F24	83
IO262NB6F24	78
IO262PB6F24	79
IO265NB6F24	76
IO265PB6F24	77
IO279NB6F26	72
IO279PB6F26	73
IO280NB6F26	70
IO280PB6F26	71
IO281NB6F26	66
IO281PB6F26	67
IO282NB6F26	64
IO282PB6F26	65
IO284NB6F26	60
IO284PB6F26	61
IO285NB6F26	58
IO285PB6F26	59
IO286NB6F26	54
IO286PB6F26	55
IO287NB6F26	52
IO287PB6F26	53
IO294NB6F27	48
IO294PB6F27	49

CQ352	
AX2000 Function	Pin Number
IO296NB6F27	46
IO296PB6F27	47
Bank 7	
IO300NB7F28	42
IO300PB7F28	43
IO303NB7F28	40
IO303PB7F28	41
IO310NB7F29	34
IO310PB7F29	35
IO311NB7F29	36
IO311PB7F29	37
IO312NB7F29	28
IO312PB7F29	29
IO315NB7F29	30
IO315PB7F29	31
IO316NB7F29	22
IO316PB7F29	23
IO317NB7F29	24
IO317PB7F29	25
IO318NB7F29	18
IO318PB7F29	19
IO320NB7F29	16
IO320PB7F29	17
IO334NB7F31	10
IO334PB7F31	11
IO335NB7F31	12
IO335PB7F31	13
IO338NB7F31	6
IO338PB7F31	7
IO341NB7F31	4
IO341PB7F31	5
Dedicated I/O	
GND	1
GND	9
GND	15

CG624	
AX1000 Function	Pin Number
GND	A8
GND	AA10
GND	AA16
GND	AA18
GND	AA21
GND	AA5
GND	AB22
GND	AB4
GND	AC10
GND	AC16
GND	AC23
GND	AC3
GND	AD1
GND	AD2
GND	AD24
GND	AD25
GND	AE1
GND	AE18
GND	AE2
GND	AE24
GND	AE25
GND	AE8
GND	B1
GND	B2
GND	B24
GND	B25
GND	C10
GND	C16
GND	C23
GND	C3
GND	D22
GND	D4
GND	E10
GND	E16
GND	E21
GND	E5

CG624	
AX1000 Function	Pin Number
GND/LP	E8
GND	H1
GND	H21
GND	H25
GND	K21
GND	K23
GND	K3
GND	L11
GND	L12
GND	L13
GND	L14
GND	L15
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	T21
GND	T23
GND	T3
GND	T5

CG624	
AX1000 Function	Pin Number
GND	V1
GND	V25
GND	V5
NC	A14
NC	AA20
NC	AB13
NC	AD4
NC	AE12
NC	F21
NC	G10
PRA	F13
PRB	A13
PRC	AB12
PRD	AE13
TCK	F5
TDI	C5
TDO	F6
TMS	D6
TRST	E6
VCCA	AB20
VCCA	F22
VCCA	F4
VCCA	J17
VCCA	J9
VCCA	K10
VCCA	K11
VCCA	K15
VCCA	K16
VCCA	L10
VCCA	L16
VCCA	R10
VCCA	R16
VCCA	T10
VCCA	T11
VCCA	T15
VCCA	T16

CG624	
AX2000 Function	**Pin Number**
IO157PB3F14	U20
IO158NB3F14	AB25
IO158PB3F14	AA25
IO160PB3F14	W24
IO161NB3F15	U24
IO161PB3F15	U23
IO162NB3F15	AA24
IO162PB3F15	Y24
IO163NB3F15	V22
IO163PB3F15	U22
IO164NB3F15	V23
IO164PB3F15	V24
IO166NB3F15	AB24
IO167NB3F15	V21
IO167PB3F15	U21
IO168NB3F15	Y23
IO168PB3F15	AA23
IO169NB3F15	W22*
IO169PB3F15	W23*
IO170NB3F15	Y22
IO170PB3F15	Y21
Bank 4	
IO171NB4F16	AC20*
IO171PB4F16	AC21*
IO172NB4F16	W20
IO172PB4F16	Y20
IO173NB4F16	AD21
IO173PB4F16	AD22
IO174NB4F16	AA19
IO176NB4F16	Y18
IO176PB4F16	Y19
IO177NB4F16	AB19

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO177PB4F16	AB18
IO182NB4F17	V19
IO182PB4F17	W19
IO183PB4F17	AC19
IO184NB4F17	AB17
IO184PB4F17	AC17
IO185NB4F17	AD19
IO185PB4F17	AD20
IO187PB4F17	AC18
IO188NB4F17	Y17
IO188PB4F17	AA17
IO189PB4F17	AE22
IO191NB4F17	W18
IO191PB4F17	V18
IO192PB4F17	U18
IO195PB4F18	AE21
IO196NB4F18	AB16
IO197NB4F18	AD17
IO197PB4F18	AD18
IO198NB4F18	V17
IO198PB4F18	W17
IO199NB4F18	AE19
IO199PB4F18	AE20
IO200NB4F18	AC15
IO201NB4F18	AD15
IO201PB4F18	AD16
IO202NB4F18	Y15
IO202PB4F18	Y16
IO206NB4F19	AB14
IO206PB4F19	AB15
IO207NB4F19	AE15
IO207PB4F19	AE16

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO208PB4F19	W16
IO209NB4F19	AE14
IO210NB4F19	V15
IO210PB4F19	V16
IO211NB4F19	AD14
IO211PB4F19	AC14
IO212NB4F19/CLKEN	W14
IO212PB4F19/CLKEP	W15
IO213NB4F19/CLKFN	AC13
IO213PB4F19/CLKFP	AD13
Bank 5	
IO214NB5F20/CLKGN	W13
IO214PB5F20/CLKGP	Y13
IO215NB5F20/CLKHN	AC12
IO215PB5F20/CLKHP	AD12
IO216NB5F20	U13
IO216PB5F20	V13
IO217NB5F20	AE10
IO217PB5F20	AE11
IO218NB5F20	W11
IO218PB5F20	W12
IO222NB5F20	AA11
IO222PB5F20	Y11
IO223PB5F21	AE9
IO225NB5F21	AE6
IO225PB5F21	AE7
IO226NB5F21	Y10
IO226PB5F21	W10
IO227PB5F21	T13
IO228NB5F21	AB10
IO228PB5F21	AB11
IO229NB5F21	AD9

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO229PB5F21	AD10
IO230NB5F21	V11
IO233NB5F21	AD7
IO233PB5F21	AD8
IO234NB5F21	V9
IO234PB5F21	V10
IO236NB5F22	AC9
IO238NB5F22	W8
IO238PB5F22	W9
IO239NB5F22	AE4
IO239PB5F22	AE5
IO240NB5F22	AB9
IO242NB5F22	AA9
IO242PB5F22	Y9
IO243NB5F22	AD5
IO243PB5F22	AD6
IO244NB5F22	U8
IO246NB5F23	AB8
IO246PB5F23	AC8
IO247NB5F23	AB7
IO247PB5F23	AC7
IO250NB5F23	AA8
IO250PB5F23	Y8
IO251NB5F23	V8
IO251PB5F23	V7
IO252NB5F23	Y7
IO252PB5F23	W7
IO253NB5F23	AC5
IO253PB5F23	AC6
IO254NB5F23	Y6
IO254PB5F23	W6
IO256NB5F23	AB6*

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO256PB5F23	AA6*
Bank 6	
IO257NB6F24	Y3
IO257PB6F24	AA3
IO258NB6F24	V3
IO258PB6F24	W3
IO259NB6F24	AA2
IO259PB6F24	AB2
IO260NB6F24	V6*
IO260PB6F24	W4*
IO262NB6F24	U4
IO262PB6F24	V4
IO263NB6F24	Y5
IO263PB6F24	W5
IO268NB6F25	U6
IO268PB6F25	U5
IO269PB6F25	U3
IO272NB6F25	T2
IO272PB6F25	U2
IO273NB6F25	W2
IO273PB6F25	Y2
IO274NB6F25	R6
IO274PB6F25	T6
IO275NB6F25	T7
IO275PB6F25	U7
IO277NB6F25	V2
IO278NB6F26	R4
IO278PB6F26	T4
IO279PB6F26	R3
IO280NB6F26	R5
IO281NB6F26	AA1
IO281PB6F26	AB1

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO284NB6F26	R8
IO284PB6F26	T8
IO285NB6F26	W1
IO285PB6F26	Y1
IO286NB6F26	P2
IO286PB6F26	R2
IO287NB6F26	T1
IO287PB6F26	U1
IO288NB6F26	P5
IO290NB6F27	P6
IO291NB6F27	P1
IO291PB6F27	R1
IO292NB6F27	P7
IO292PB6F27	R7
IO293NB6F27	M1
IO293PB6F27	N1
IO294NB6F27	P8
IO296NB6F27	N3
IO296PB6F27	P3
IO298NB6F27	N4
IO298PB6F27	P4
IO299NB6F27	M2
IO299PB6F27	N2
Bank 7	
IO300NB7F28	P9*
IO300PB7F28	N6*
IO302NB7F28	M6
IO304NB7F28	N8
IO304PB7F28	N7
IO308NB7F28	M4
IO309NB7F28	L3
IO309PB7F28	M3

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
VCCIB2	D23
VCCIB2	E22
VCCIB2	K17
VCCIB2	L17
VCCIB2	M16
VCCIB3	AA22
VCCIB3	AB23
VCCIB3	AC24
VCCIB3	AC25
VCCIB3	P16
VCCIB3	R17
VCCIB3	T17
VCCIB4	AB21
VCCIB4	AC22
VCCIB4	AD23
VCCIB4	AE23
VCCIB4	T14
VCCIB4	U15
VCCIB4	U16
VCCIB5	AB5
VCCIB5	AC4
VCCIB5	AD3
VCCIB5	AE3
VCCIB5	T12
VCCIB5	U10
VCCIB5	U11
VCCIB6	AA4
VCCIB6	AB3
VCCIB6	AC1
VCCIB6	AC2
VCCIB6	P10
VCCIB6	R9

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
VCCIB6	T9
VCCIB7	C1
VCCIB7	C2
VCCIB7	D3
VCCIB7	E4
VCCIB7	K9
VCCIB7	L9
VCCIB7	M10
VCCPLA	E12
VCCPLB	J12
VCCPLC	E14
VCCPLD	H14
VCCPLE	Y14
VCCPLF	U14
VCCPLG	Y12
VCCPLH	U12
VCOMPLA	F12
VCOMPLB	H12
VCOMPLC	F14
VCOMPLD	J14
VCOMPLE	AA14
VCOMPLF	V14
VCOMPLG	AA12
VCOMPLH	V12
VPUMP	E20

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

Revision	Changes	Page
Revision 8 (continued)	The following changes were made in the "FG676"(AX500) section: AE2, AE25 Change from NC to GND. AF2, AF25 Changed from GND to NC AB4, AF24, C1, C26 Changed from V_{CCDA} to V_{CCA} AD15 Change from V_{CCDA} to V_{COMPLE} AD17 Changed from V_{COMPLE} to V_{CCDA}	3-37
	In the "FG896" (AX2000) section, the AK28 changed from VCCIB5 to VCCIB4.	3-52
	The "CQ352" and "CG624" sections are new.	3-98, 3-115
Revision 7 (Advance v1.6)	All I/O FIFO capability was removed.	n/a
	Table 1 was updated.	i
	Figure 1-9 was updated.	1-7
	Figure 2-5 was updated.	2-16
	The "Using an I/O Register" section was updated.	2-16
	The AX250 and AX1000 descriptions were added to the "FG484"section.	3-21
Revision 6 (Advance v1.5)	Table 2-3 was updated.	2-2
	Figure 2-1 was updated.	2-8
	Figure 2-48 was updated.	2-75
	Figure 2-52 was updated.	2-82
Revision 5 (Advance v1.4)	In the "PQ208" table, pin 196 was missing, but it has been added in this version with a function of GND.	3-84
	The following pins in the "FG484" table for AX500 were changed: Pin G7 is GND/LP Pins AB8, C10, C11, C14, AB16 are NC.	3-21
	The "FG676" table was updated.	3-37
Revision 4 (Advance v1.3)	The "Device Resources" section was updated for the CS180.	ii
	The "Programmable Interconnect Element" and Figure 1-2 are new.	1-1 and 1-2
	The "CS180" table is new.	3-1
	The "PQ208" tables for the AX500 were updated. The following pins were not defined in the previous version: GND 21 IO106PB5F10/CLKHP 71 GND 136	3-84
Revision 3 (Advance v1.2)	Table 1, "Ordering Information", "Device Resources", and the Product Plan table were updated.	i, ii
	The following figures and tables were updated: Figure 1-3 Figure 1-8 (new) Table 2-3 Figure 2-2 Table 2-8 Figure 2-11	 1-2 1-6 2-2 2-9 2-12 2-23
	The "Design Environment" section was updated.	1-7
	The "Package Thermal Characteristics" was updated.	2-6